

Does JCET Group offer optical module packaging and testing services



Overview

JCET offers the broadest portfolios of comprehensive packaging and test services in the semiconductor industry and can leverage its strong packaging and test capabilities to provide a full turnkey solution of integrated packaging, testing, and direct shipment to end customers. April 21, 2026 -- Driven by the surging demand for High-Performance Computing (HPC) and high-density storage, high-end advanced packaging has emerged as a primary catalyst for the evolution of the semiconductor industry. Capitalizing on this momentum, JCET Group has significantly accelerated its. Driving the Future of Data Connectivity with Co-Packaged Optics (CPO) JCET's latest CPO packaging solutions deliver higher bandwidth, lower power, and improved signal integrity — enabling next-generation performance for computing, communications, and automotive applications. By integrating optical. Founded in 1972, JCET Group is the world's leading integrated circuit manufacturing and technology services provider. JCET Group primarily serves sectors such as mobile, communication, compute, consumer, automotive, and industrial.



Article Content

JCET Group — Test Solutions

JCET's certificated Quality Test Center provides reliability tests, including environmental reliability tests, life reliability tests, and board level reliability tests; and a full range of failure analysis services.

JCET Group — Edge AI

JCET provides a full range of advanced packaging and testing solutions, including 2.5D/3D packaging, wafer-level packaging, system-in-package (SiP), etc., and one-stop solutions, including collaborative

JCET Group

JCET delivers world-class services to its customers. The greatest value from doing business with JCET is realized when engaging JCET as a full turnkey solutions provider - including IC design and

JCET Group — News Detail

Enhancing this foundation, the RFFE module utilizes fully integrated designs, advanced materials, and system-level packaging innovations to meet the demands of the smart era and deliver

JCET Advanced Packaging

The company offers packaging and test services, including wafer bumping, probing, grinding, and various IC packaging solutions, as well as RF, analog, digital, and mixed signal testing.

JCET Group — Turnkey Services

JCET offers the broadest portfolios of comprehensive packaging and test services in the semiconductor industry and can leverage its strong packaging and test capabilities to provide a full turnkey solution

JCET Accelerates Strategic Shift Toward High-End Advanced

For high-performance computing and storage scenarios such as HPC data centers, JCET has developed a systematic portfolio of packaging and testing solutions covering computing, storage,

JCET's New High-End Packaging Plant in China

According to a report from UDN, China's largest semiconductor packaging and testing company, JCET, has completed the planning and

JCET Group — News Detail

Shanghai, China, January 21 — JCET Group today announced a key milestone in co-packaged optics (CPO). The company has delivered customer samples of its silicon photonics engine developed on

JCET Group Co., Ltd.

JCET Group is a leading global semiconductor system integration packaging and test provider, offering a full range of turnkey services that include semiconductor package integration design and ...

Top 10 semiconductor package testing suppliers

Company profile JCET Group is the world's leading integrated-circuit manufacturing and technology services provider, offering a full range of turnkey

JCET Group — Home

The greatest value from doing business with JCET is realized when engaging JCET as a full turnkey solutions provider—from IC design through test program development, wafer bump, wafer probe, multi

JCET Group — Power Device Packaging

In power and analog device manufacturing, JCET leverages extensive expertise in wafer processing, advanced architectures, and high-temperature/thermal-diffusion materials.

JCET (company)

JCET Group is the largest Outsourced Semiconductor Assembly and Test (OSAT) company in mainland China and the third-largest globally. JCET also provides semiconductor manufacturing, product

JCET Group — Packaging Solutions

JCET offers a full spectrum of semiconductor packaging services to meet diverse customer needs, spanning lead-frame packaging, substrate-based packaging, flip-chip interconnects, and advanced

JCET's Co-Packaged Optics: Enabling Next-Gen Performance

By integrating optical engines with ASICs in a single package, we achieve shorter optical paths, optimized thermal management, and reliable system-level performance.

JCET Group — Home

JCET delivers world-class services to its customers. The greatest value from doing business with JCET is realized when engaging JCET as a full turnkey solutions provider—from IC design through test

JCET: Semiconductor Packaging and Testing, the State of the Art

Yaojian Lin, VP of Engineering and General Manager of R& D Center, JCET Group
Speech Title: Packaging Fundamentals of High-Performance Applications • Si node technology in IC scaling is becoming ...

JCET Group | Semiconductor Materials and Equipment

Our comprehensive portfolio covers a wide spectrum of semiconductor applications such as mobile, communication, compute, consumer, automotive and industry etc., through advanced wafer level

JCET Group — Automotive

JCET is also actively promoting the mass production applications of core materials such as ceramic substrates for new energy power module packaging (DBC/DBA/AMB), aluminum wire, aluminum

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